



NOTE:

- This data is supplied for general information only and is believed to be correct at the time of publication.
- For critical applications, the customer is advised to verify device revision and pad coordinates, prior to processing
- Changes can be made without notification from the manufacturer. Diedevices cannot accept liability in that event

DEVICE	AM30P20-500	DIE SIZE (MILS)	58 X 93 X 7
MANUFACTURER	ANALOG POWER	BOND PADS MIN (MILS)	14 X 19
APPROVED BY	GEW	TOP METAL	Al
DATE	25/11/20	BACK METAL	Ti/Ni/Ag
SERIAL NUMBER	0876	BACK POTENTIAL	DRAIN

